

EuroSimE 2026

27th International Conference on Thermal, Mechanical and Multi-Physics Simulation and Experiments in Microelectronics and Microsystems

Warsaw, Poland | April 19–22, 2026

More information at www.eurosim.org

FIRST CALL FOR PAPERS

The 27th EuroSimE conference will take place in Warsaw, Poland from April 19 to 22, 2026. As Poland's dynamic capital, Warsaw combines centuries of history with innovation and energy. The conference will present the results of fundamental research and industrial applications of thermal, mechanical, and multiphysics simulations and experiments of micro/nanoelectronics and microsystems.

On April 19, 2026, professional training courses will be offered, followed by three days of technical sessions from April 20 to 22, 2026, comprising oral and poster presentations. These sessions will include industry keynote talks given by invited speakers holding leading industrial positions, who will highlight major technological and industrial development trends, challenges, and roadmaps. In addition, technical keynote talks will address critical issues in modeling and experimentation for microelectronics and microsystems. In parallel, an exhibition of suppliers of experimental characterization equipment and simulation/optimization software will demonstrate their latest features. Accepted papers will be submitted for inclusion in the IEEE Xplore digital library. The best papers will be selected for publication in the Microelectronics Reliability Journal from Elsevier and the Micromachines Journal from MDPI. Candidates for the best papers will be preselected based on abstracts that clearly highlight the scope, approach, and major results of the proposed contributions.

Single domain simulation

- Thermal, mechanical, thermo-mechanical, vibration, shock
- Chip package board interaction
- Advanced numerical and analytical simulations methodologies and tools
- Compact Modelling & Model Order Reduction
- Digital twins
- Advanced thermal management concepts

Material characterization and validation

- Material characterization, experiments and modelling
- Bulk and interface toughness, characterization and modeling
- Experimental methods for validation of simulation models
- Failure analysis and failure mode extraction
- Failure criteria and damage modelling for reliability prediction

Application domains

- Electronic components, packaging and system integration for applications including aerospace, automotive, energy, lighting and medical.
- MEMS sensors & actuators, piezoelectric, piezoresistive, functional ceramic sensors and components
- Opto-electronic & opto-mechanical devices
- Nano-electronic mechanical devices
- Consumer electronics

Multi-physics simulation

- Multi-physics simulation (MEMS, manufacturing and process models, electronic control unit/system level, fluid structure interactions)
- Multi-scale modelling and simulation
- Integrated process modelling
- Simulation-based optimization, virtual prototyping and pre-qualification in product and process design
- Simulations for heterogeneous integration

Emerging modeling methods and tools

- Prognostics and Health Management (PHM)
- Development and implementation of artificial intelligence and machine learning
- Use of big data in simulation & reliability applications
- 3D packaging, TSV technology, heterogeneous integration, chiplet packaging
- Additive manufacturing (3D printing) for electronics

Important dates

Abstract submission deadline: **November 04, 2025**

Notification of acceptance: **December 19, 2025**

Full manuscript submission deadline: **March 9, 2026**



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**Abstract submission through ConfTool
will open in September 2025**